

## 1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

|                |         |
|----------------|---------|
| Part Number :  | CJS8820 |
| Package Type : | TSSOP8  |

## 2. MATERIAL ANALYSIS DATA SHEET

| Material      | Composition      | CAS No.      | % of weight | % of weight total |
|---------------|------------------|--------------|-------------|-------------------|
| Wafer         | Silicon          | 7440-21-3    | 100.00%     | 2.5063%           |
| Lead Frame    | Cu               | 7440-50-8    | 97.43%      | 58.5866%          |
|               | Fe               | 7439-89-6    | 2.30%       |                   |
|               | P                | 7723-14-0    | 0.10%       |                   |
|               | Zn               | 7440-66-6    | 0.15%       |                   |
|               | Pb               | 7439-92-1    | 0.01%       |                   |
|               | Silver           | 7440-22-4    | 0.01%       |                   |
| Epoxy         | Silver           | 7440-22-4    | 79.00%      | 1.0131%           |
|               | Epoxy resin      | 9003-36-5    | 5.99%       |                   |
|               | Diluent A        | 3101-60-8    | 3.99%       |                   |
|               | Diluent B        | 80-08-0      | 4.27%       |                   |
|               | Diluent C        | Trade Secret | 2.10%       |                   |
|               | Hardener A       | Trade Secret | 1.69%       |                   |
|               | Hardener B       | Trade Secret | 2.89%       |                   |
|               | Solvent          | Trade Secret | 0.02%       |                   |
|               | Organic Peroxide | Trade Secret | 0.06%       |                   |
| Wire1         | Cu               | 7440-50-8    | 100.00%     | 1.4028%           |
| Wire2         | Cu               | 7440-50-8    | 97.55%      |                   |
|               | Pd               | 7440-05-3    | 2.40%       |                   |
| Mold Compound | Epoxy Resin1     | Trade Secret | 6.80%       | 35.2255%          |
|               | Epoxy Resin2     | Trade Secret | 4.70%       |                   |
|               | Phenol Resin     | Trade Secret | 5.30%       |                   |
|               | Carbon black     | 1333-86-4    | 0.20%       |                   |
|               | Amorphous silica | 60676-86-0   | 83.00%      |                   |
| Plating       | Tin              | 7440-31-5    | 100.00%     | 2.6684%           |

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.